

# High Temperature Silicon Carbide Power Schottky Diode

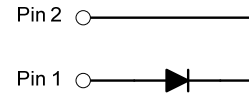
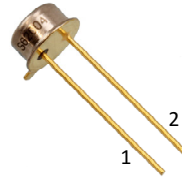
|                              |   |       |
|------------------------------|---|-------|
| $V_{RRM}$                    | = | 100 V |
| $I_F (T_C=25^\circ\text{C})$ | = | 4 A   |
| $Q_C$                        | = | 9 nC  |

## Features

- 100 V Schottky rectifier
- 210 °C maximum operating temperature
- Zero reverse recovery charge
- Superior surge current capability
- Positive temperature coefficient of  $V_F$
- Temperature independent switching behavior
- Lowest figure of merit  $Q_C/I_F$
- Available screened to Mil-PRF-19500

## Package

- RoHS Compliant



TO – 46

## Advantages

- High temperature operation
- Improved circuit efficiency (Lower overall cost)
- Low switching losses
- Ease of paralleling devices without thermal runaway
- Smaller heat sink requirements
- Industry's lowest reverse recovery charge
- Industry's lowest device capacitance
- Ideal for output switching of power supplies
- Best in class reverse leakage current at operating temperature

## Applications

- Down Hole Oil Drilling
- Geothermal Instrumentation
- Solenoid Actuators
- General Purpose High-Temperature Switching
- Amplifiers
- Solar Inverters
- Switched-Mode Power Supply (SMPS)
- Power Factor Correction (PFC)

## Maximum Ratings at $T_j = 210^\circ\text{C}$ , unless otherwise specified

| Parameter  | Symbol         | Conditions                                      | Values |            |      | Unit             |
|--|----------------|---|--------|------------|------|------------------|
|  |                |   | min.   | typ.       | max. |                  |
| Repetitive peak reverse voltage                      | $V_{RRM}$      |   |        | 100        |      | V                |
| Continuous forward current                           | $I_F$          | $T_C = 25^\circ\text{C}$                        |        | 4          |      | A                |
| Continuous forward current                           | $I_F$          | $T_C \leq 180^\circ\text{C}$                    |        | 2          |      | A                |
| RMS forward current                                  | $I_{F(RMS)}$   | $T_C \leq 180^\circ\text{C}$                    |        | 4          |      | A                |
| Surge non-repetitive forward current, Half Sine Wave | $I_{F,SM}$     | $T_C = 25^\circ\text{C}, t_p = 10\text{ ms}$    |        | 10         |      | A                |
| Non-repetitive peak forward current                  | $I_{F,max}$    | $T_C = 25^\circ\text{C}, t_p = 10\ \mu\text{s}$ |        | 65         |      | A                |
| $i^2t$ value   | $\int i^2 dt$  | $T_C = 25^\circ\text{C}, t_p = 10\text{ ms}$    |        | 0.5        |      | A <sup>2</sup> S |
| Power dissipation                                    | $P_{tot}$      | $T_C = 25^\circ\text{C}$                        |        | 64         |      | W                |
| Operating and storage temperature                    | $T_j, T_{stg}$ |   |        | -55 to 210 |      | °C               |

## Electrical Characteristics at $T_j = 210^\circ\text{C}$ , unless otherwise specified

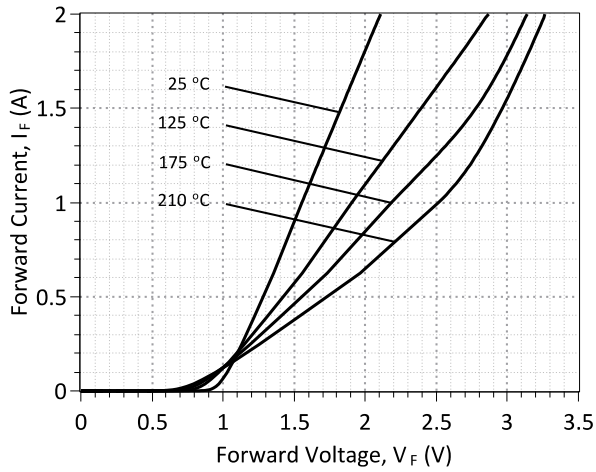
| Parameter               | Symbol | Conditions  | Values               |      |      | Unit          |
|-------------------------|--------|---|----------------------|------|------|---------------|
|                         |        |   | min.                 | typ. | max. |               |
| Diode forward voltage   | $V_F$  | $I_F = 1\text{ A}, T_j = 25^\circ\text{C}$  |                      | 1.6  |      | V             |
|                         |        | $I_F = 1\text{ A}, T_j = 210^\circ\text{C}$   |                      | 2.6  |      |               |
| Reverse current         | $I_R$  | $V_R = 100\text{ V}, T_j = 25^\circ\text{C}$  |                      | 1    | 5    | $\mu\text{A}$ |
|                         |        | $V_R = 100\text{ V}, T_j = 210^\circ\text{C}$   |                      | 5    | 50   |               |
| Total capacitive charge | $Q_C$  | $I_F \leq I_{F,MAX}$<br>$di_F/dt = 200\text{ A}/\mu\text{s}$<br>$T_j = 210^\circ\text{C}$ | $V_R = 100\text{ V}$ | 9    |      | nC            |
| Switching time          | $t_s$  | $T_j = 210^\circ\text{C}$   | $V_R = 100\text{ V}$ | < 17 |      | ns            |
| Total capacitance       | C      | $V_R = 1\text{ V}, f = 1\text{ MHz}, T_j = 25^\circ\text{C}$                              |                      | 76   |      | pF            |
|                         |        | $V_R = 100\text{ V}, f = 1\text{ MHz}, T_j = 25^\circ\text{C}$                            |                      | 20   |      |               |

## Thermal Characteristics

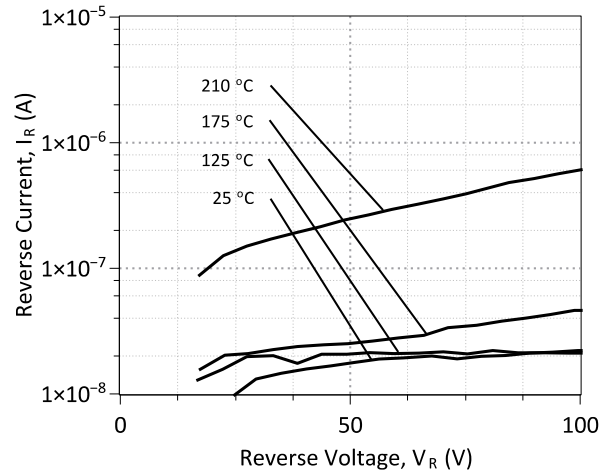
|                                     |            |      |      |
|-------------------------------------|------------|------|------|
| Thermal resistance, junction - case | $R_{thJC}$ | 5.55 | °C/W |
|-------------------------------------|------------|------|------|

## Mechanical Properties

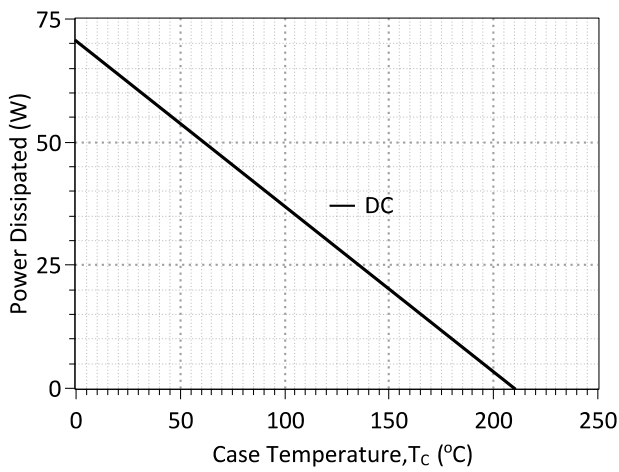
|                 |   |     |    |
|-----------------|---|-----|----|
| Mounting torque | M | 0.6 | Nm |
|-----------------|---|-----|----|



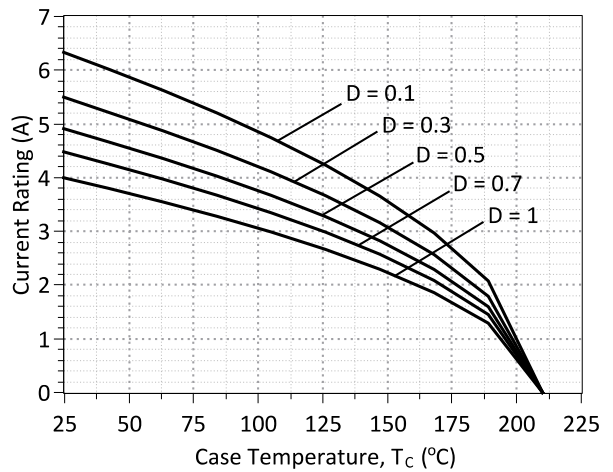
**Figure 1: Typical Forward Characteristics**



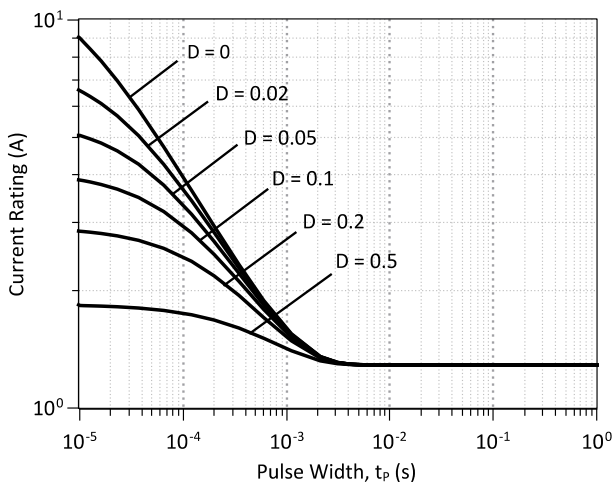
**Figure 2: Typical Reverse Characteristics**



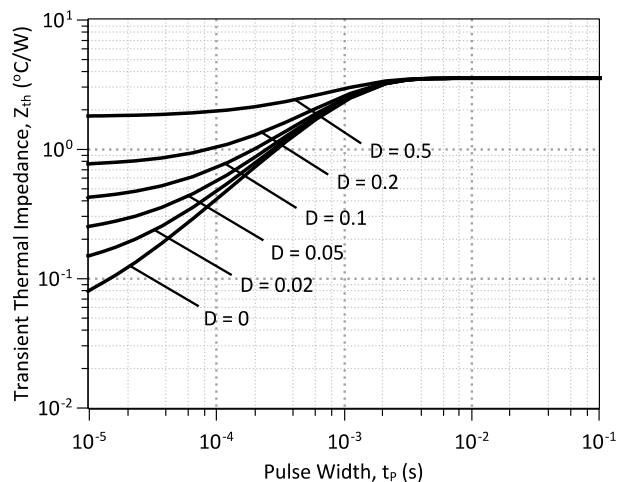
**Figure 3: Power Derating Curve**



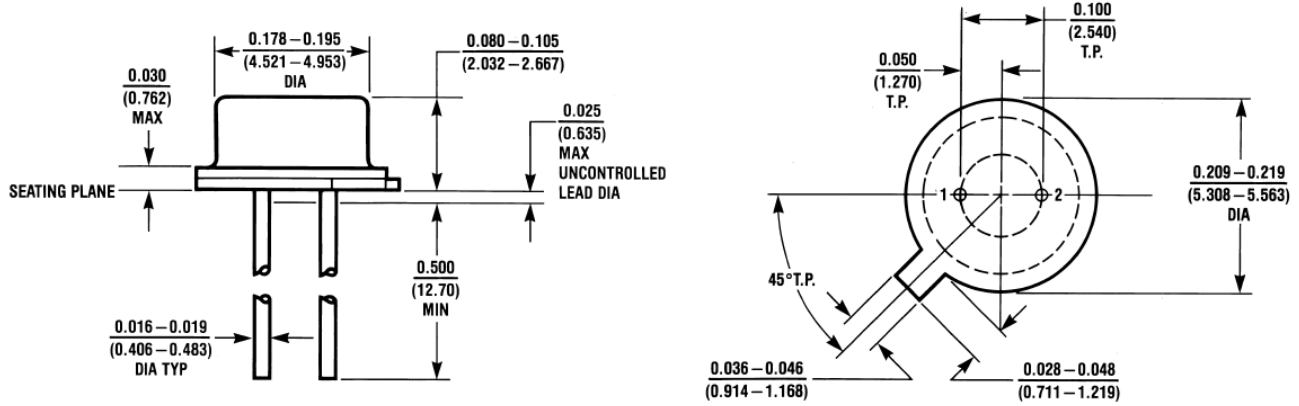
**Figure 4: Current Derating Curves ( $D = t_p/T$ ,  $t_p = 400 \mu s$ )  
(Considering worst case  $Z_{th}$  conditions)**



**Figure 5: Current vs Pulse Duration Curves at  $T_C = 190 \text{ } ^\circ\text{C}$**



**Figure 6: Transient Thermal Impedance**

**Package Dimensions:**
**TO-46**
**PACKAGE OUTLINE**

**NOTE**

1. CONTROLLED DIMENSION IS INCH.
2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS

**Revision History**

| Date       | Revision | Comments        | Supersedes |
|------------|----------|-----------------|------------|
| 2014/08/29 | 0        | Initial release |            |
|            |          |                 |            |

Published by

GeneSiC Semiconductor, Inc.  
 43670 Trade Center Place Suite 155  
 Dulles, VA 20166

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## SPICE Model Parameters

This is a secure document. Copy this code from the SPICE model PDF file on our website into a SPICE software program for simulation of the GB02SHT01-46.

```
*      MODEL OF GeneSiC Semiconductor Inc.
*
*      $Revision:   1.0           $
*      $Date:      29-AUG-2014   $
*
*      GeneSiC Semiconductor Inc.
*      43670 Trade Center Place Ste. 155
*      Dulles, VA 20166
*
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*      These models are provided "AS IS, WHERE IS, AND WITH NO WARRANTY
*      OF ANY KIND EITHER EXPRESSED OR IMPLIED, INCLUDING BUT NOT LIMITED
*      TO ANY IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A
*      PARTICULAR PURPOSE."
*      Models accurate up to 2 times rated drain current.
*
*      Start of GB02SHT01-46 SPICE Model
*
.SUBCKT GB02SHT01ANODE KATHODE
D1 ANODE KATHODE GB02SHT01_25C; Call the Schottky Diode Model
D2 ANODE KATHODE GB02SHT01_PIN; Call the PiN Diode Model
.MODEL GB02SHT01_25C D
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+ TRS1    0.0057      TRS2    2.40E-05
+ N       1           IKF     322
+ EG      1.2         XTI     3
+ CJO     9.12E-11    VJ      0.371817384
+ M       1.527759838 FC      0.5
+ TT      1.00E-10    BV      100
+ IBV     1.00E-03   VPK     100
+ IAVE    2           TYPE    SiC_Schottky
+ MFG     GeneSiC_Semiconductor
.MODEL GB02SHT01_PIN D
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+ N       5           IKF     800
+ EG      3.23        XTI     -14
+ FC      0.5         TT      0
+ BV      100         IBV     1.00E-03
+ VPK     100         IAVE    2
+ TYPE    SiC_PiN
.ENDS
*
*      End of GB02SHT01 SPICE Model
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